

ABSTRACT

A synthetic resin card in which card warpage can be reduced and a method for producing the same are provided.

- 5 By setting the difference  $\Delta$  in the angle of orientation between outer layers symmetrically laminated on a card core section, it is possible to reduce imbalance of stress resulting from the difference in the shrinkage factor between the outer layers, and card warpage can be suppressed.
- 10 Furthermore, by setting the thickness of the outer layers at 25  $\mu\text{m}$  to 125  $\mu\text{m}$ , rising of the surface of the synthetic resin card can be reduced. By reducing the card warpage and the rising of the surface of the synthetic resin card, it is possible to improve moving characteristics when the
- 15 synthetic resin card is allowed to move in a device.